FAIRCHILD™

March 2016
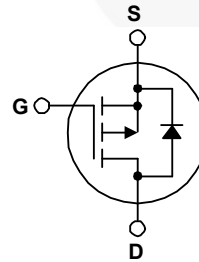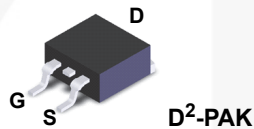
FQB34P10

P-Channel QFET® MOSFET

100 V, -33.5 A, 60 mΩ

Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- -33.5 A, -100 V, $R_{DS(on)}$ = 60 mΩ (Max.) @ V_{GS} = .10 V, I_D = -16.75 A
- Low Gate Charge (Typ. 85 nC)
- Low Crss (Typ. 170 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating

D²-PAK

Absolute Maximum Ratings
T_C = 25°C unless otherwise noted.

Symbol	Parameter			FQB34P10TM	Unit
V_{DSS}	Drain-Source Voltage			-100	V
I_D	Drain Current	- Continuous (T_C = 25°C)		-33.5	A
		- Continuous (T_C = 100°C)		-23.5	A
I_{DM}	Drain Current	- Pulsed	(Note 1)	-134	A
V_{GSS}	Gate-Source Voltage			± 25	V
E_{AS}	Single Pulsed Avalanche Energy		(Note 2)	2200	mJ
I_{AR}	Avalanche Current		(Note 1)	-33.5	A
E_{AR}	Repetitive Avalanche Energy		(Note 1)	15.5	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	-6.0	V/ns
P_D	Power Dissipation (T_A = 25°C) *			3.75	W
	Power Dissipation (T_C = 25°C)			155	W
	- Derate above 25°C			1.03	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range			-55 to +175	°C
T_L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FQB34P10TM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.97	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	
	Thermal Resistance, Junction to Ambient (*1 in² Pad of 2-oz Copper), Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQB34P10TM	FQB34P10	D²-PAK	Tape and Reel	330 mm	24 mm	800 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = -250 μA	-100	--	--	V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C	--	-0.1	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -100 V, V_{GS} = 0 V	--	--	-1	μA
		V_{DS} = -80 V, T_C = 150°C	--	--	-10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = -25 V, V_{DS} = 0 V	--	--	-100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = 25 V, V_{DS} = 0 V	--	--	100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250 μA	-2.0	--	-4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = -10 V, I_D = -16.75 A	--	0.049	0.06	Ω
g_{FS}	Forward Transconductance	V_{DS} = -40 V, I_D = -16.75 A	--	23	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = -25 V, V_{GS} = 0 V, f = 1.0 MHz	--	2240	2910	pF
C_{oss}	Output Capacitance		--	730	950	pF
C_{rss}	Reverse Transfer Capacitance		--	170	220	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = -50 V, I_D = -33.5 A, R_G = 25 Ω	--	25	60	ns
t_r	Turn-On Rise Time		--	250	510	ns
$t_{d(off)}$	Turn-Off Delay Time		--	160	330	ns
t_f	Turn-Off Fall Time	(Note 4)	--	210	430	ns
Q_g	Total Gate Charge	V_{DS} = -80 V, I_D = -33.5 A, V_{GS} = -10 V	--	85	110	nC
Q_{gs}	Gate-Source Charge		--	15	--	nC
Q_{gd}	Gate-Drain Charge	(Note 4)	--	45	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	-33.5	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	-134	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = -33.5 A	--	--	-4.0	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S = -33.5 A, dI_F / dt = 100 A/μs	--	160	--	ns
Q_{rr}	Reverse Recovery Charge		--	0.88	--	μC

Notes:
1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = mH, I_{AS} = -33.5A, V_{DD} = -25 V, R_G = 25 Ω, starting T_J = 25°C.
3. $I_{SD} \leq$ -33.5 A, di/dt $\leq$ 300 A/μs , $V_{DD} \leq BV_{DSS}$, starting T_J = 25°C.
4. Essentially independent of operating temperature.
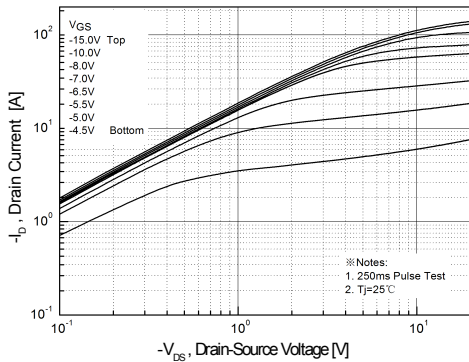
Typical Characteristics

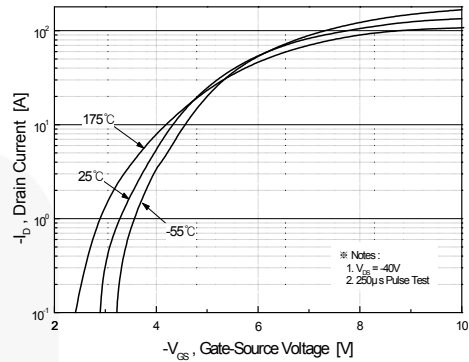**Figure 1. On-Region Characteristics**
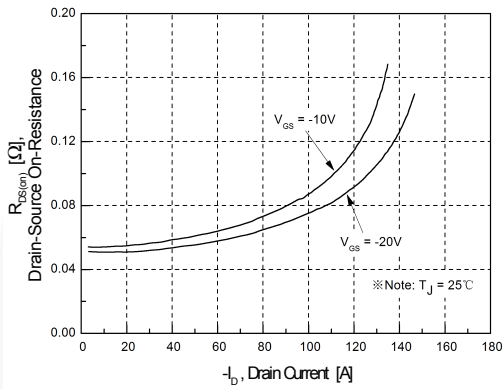
Figure 2. Transfer Characteristics

Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage
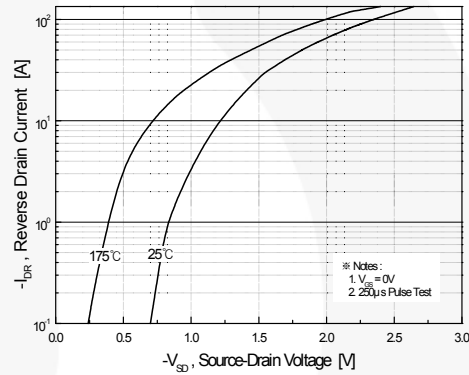
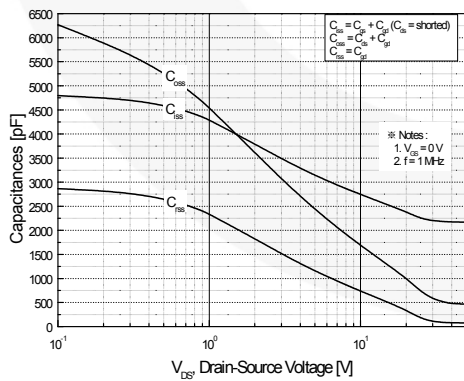**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**
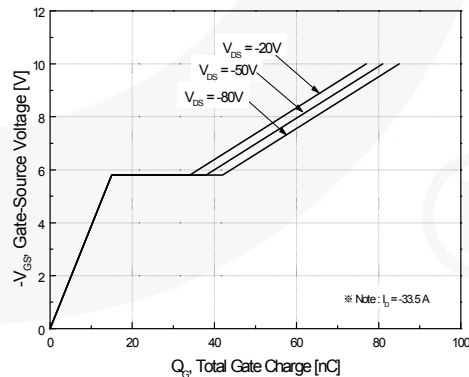
Figure 5. Capacitance Characteristics

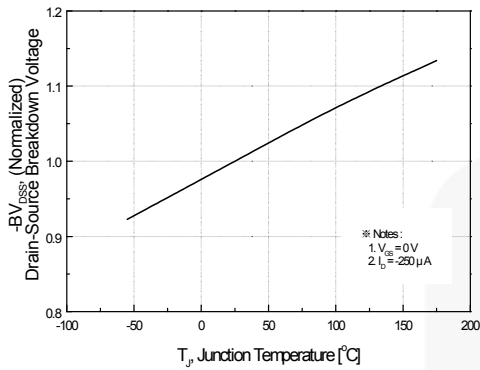**Figure 6. Gate Charge Characteristics**

Typical Characteristics (Continued)
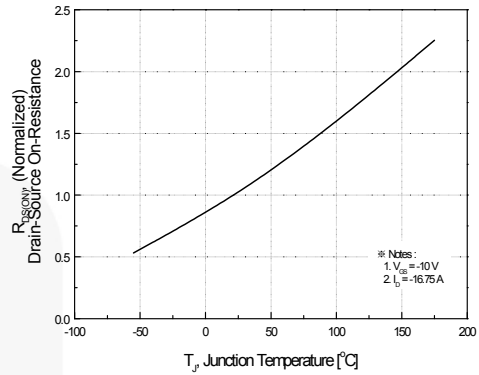

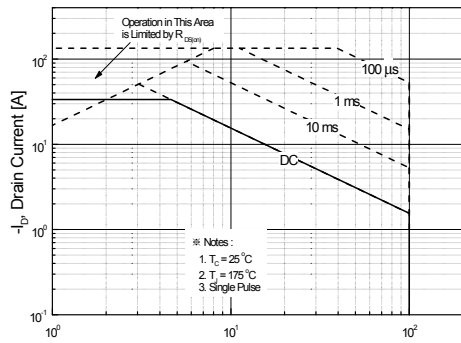**Figure 7. Breakdown Voltage Variation vs. Temperature**

Figure 8. On-Resistance Variation vs. Temperature

Figure 9. Maximum Safe Operating Area
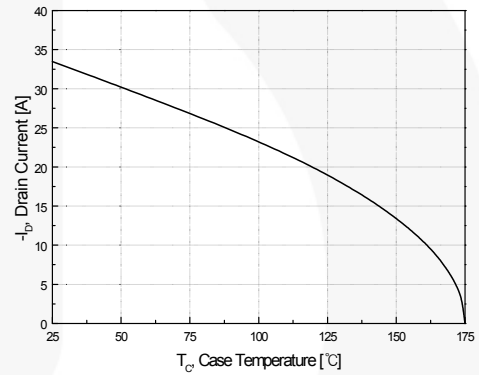
Figure 10. Maximum Drain Current vs. Case Temperature
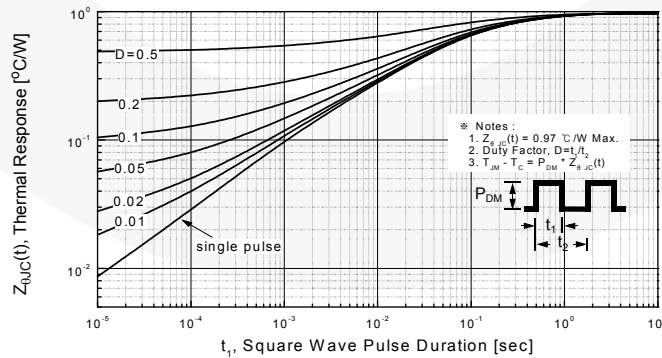
Figure 11. Transient Thermal Response Curve
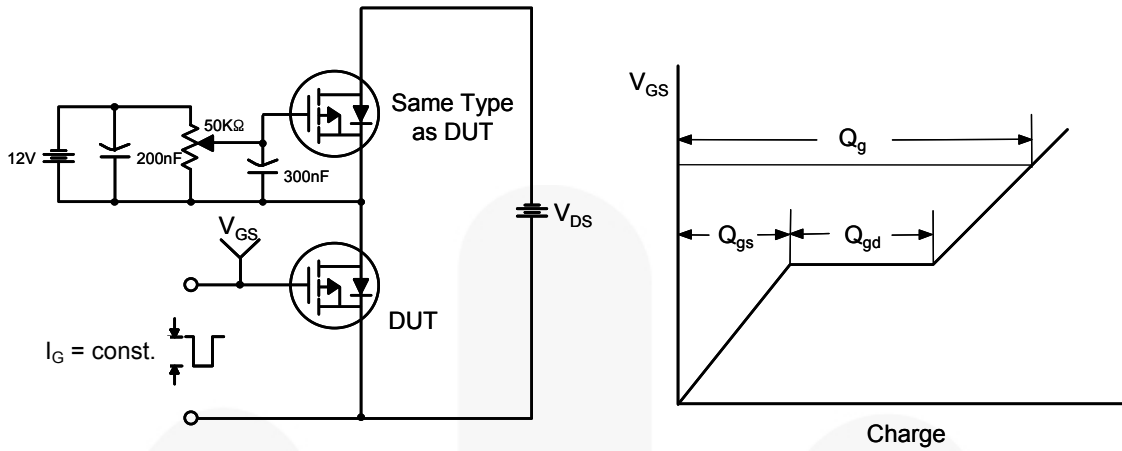
Figure 12. Gate Charge Test Circuit & Waveform
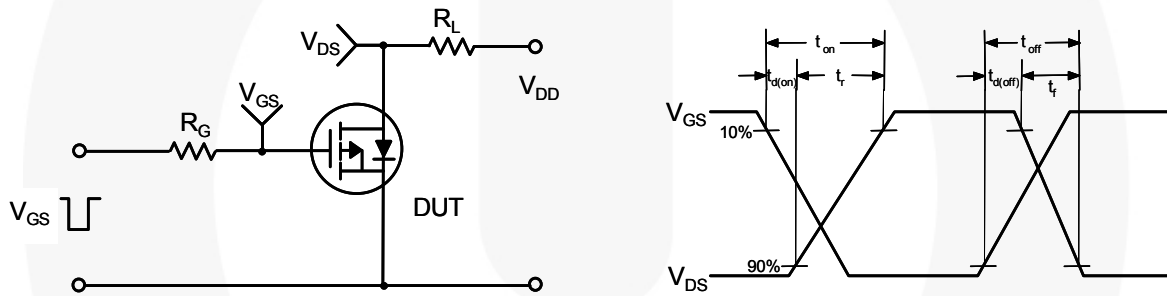
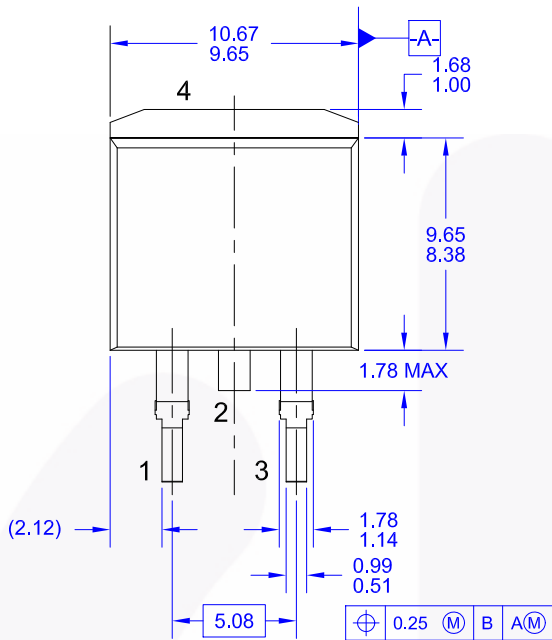

Figure 13. Resistive Switching Test Circuit & Waveforms

$$E_{AS} = \frac{1}{2} L I_{AS}^2 \; \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$
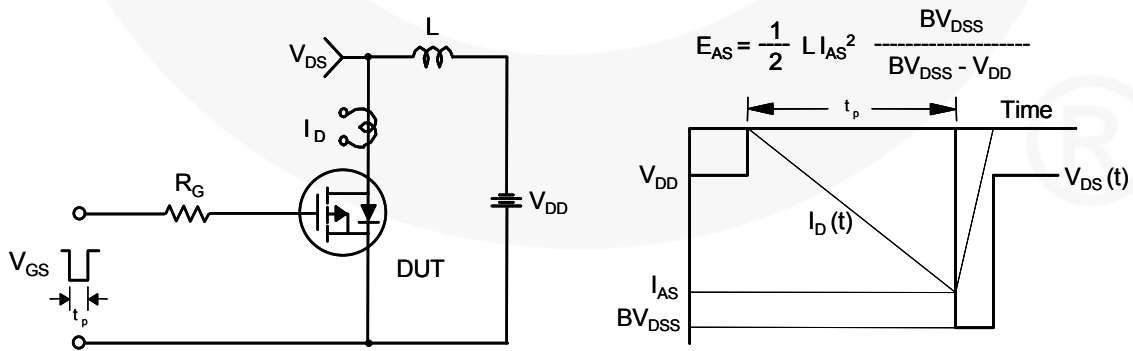
Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

$$D = \frac{\text{Gate Pulse Width}}{\text{Gate Pulse Period}}$$
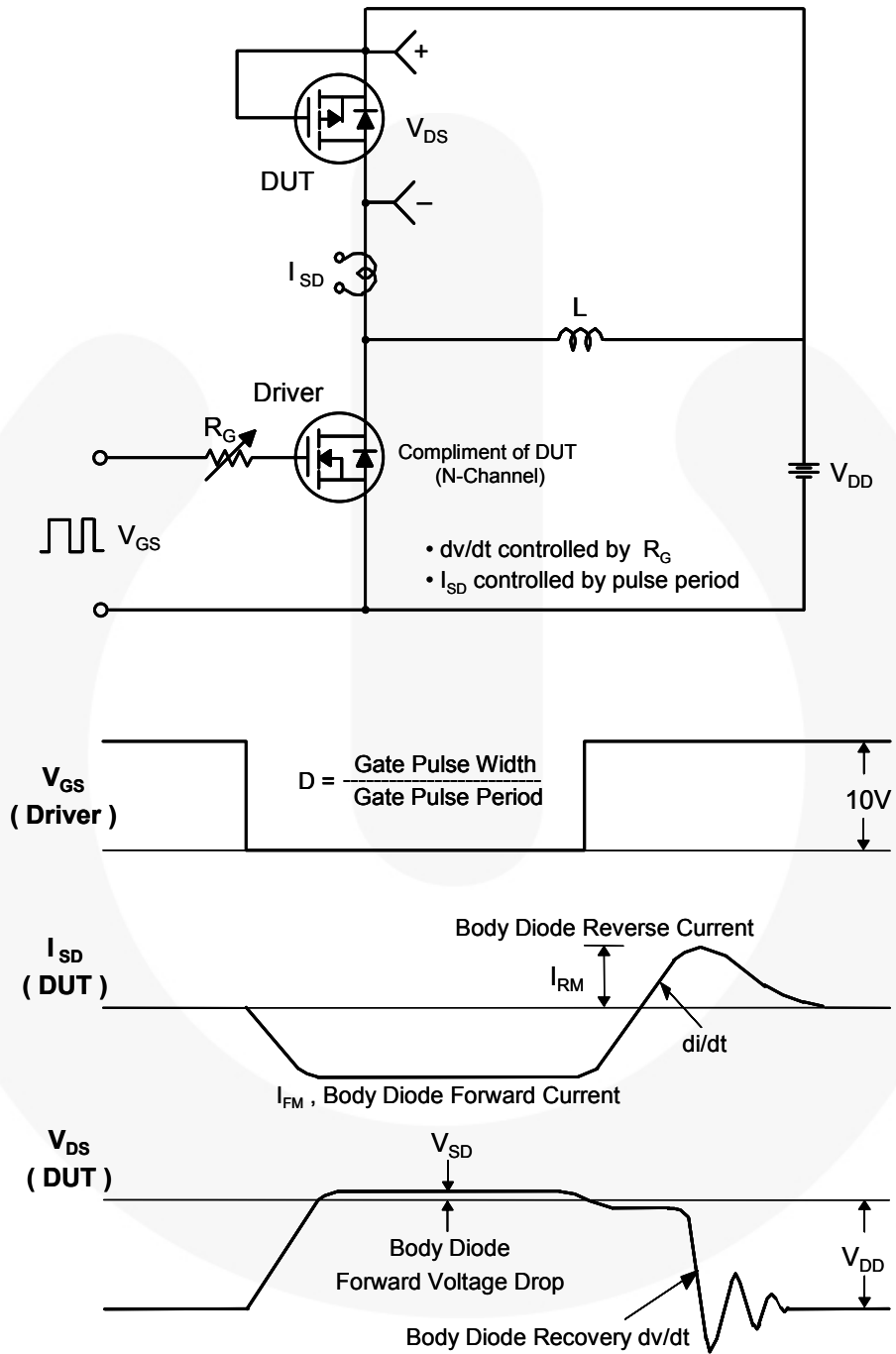
Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

10.67
9.65

-A-

1.68
1.00

4

9.65
8.38

1.78 MAX

2

1

3

(2.12)

1.78
1.14

0.99
0.51

5.08

⊕ | 0.25 Ⓜ | B | AⓂ

12.70

9.45

10.00

(6.40)

3.80

1.05

5.08
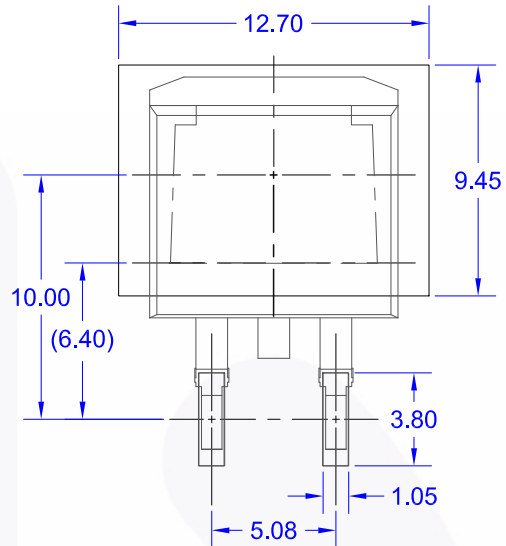
LAND PATTERN RECOMMENDATION
UNLESS NOTED, ALL DIMS TYPICAL

6.22 MIN

4

6.86 MIN

2

3

1

-B-

4.83
4.06

1.65
1.14

15.88
14.61

SEE
DETAIL A

GAGE PLANE

0.74
0.33

8°
0°

0.25

2.79
1.78

8°
0°

⌓ | 0.10 | B

0.25 MAX

(5.38)

SEATING
PLANE

DETAIL A, ROTATED 90°
SCALE: 2X
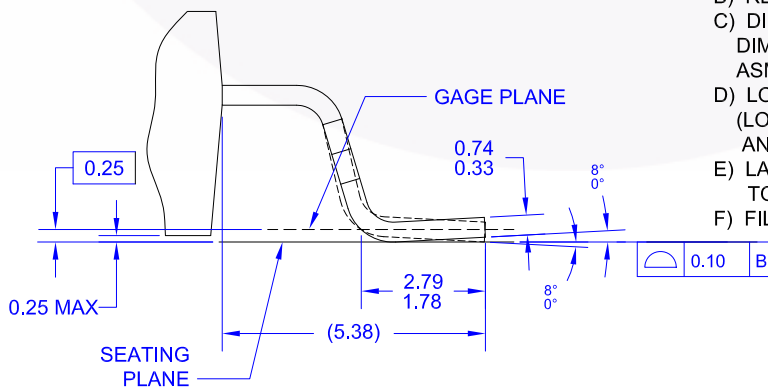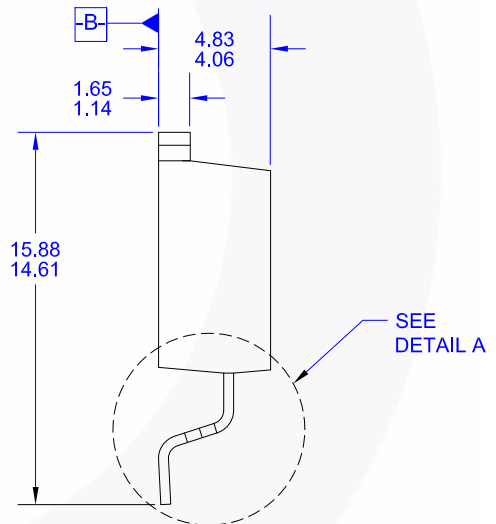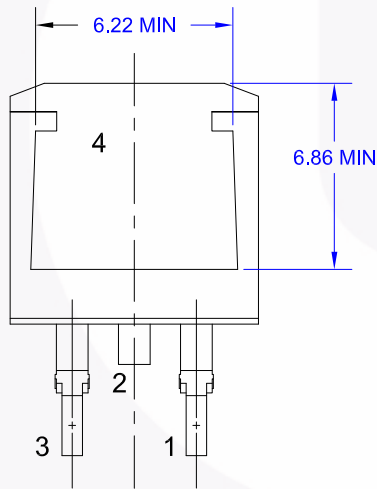
NOTES: UNLESS OTHERWISE SPECIFIED
A) ALL DIMENSIONS ARE IN MILLIMETERS.
B) REFERENCE JEDEC, TO-263, VARIATION AB.
C) DIMENSIONING AND TOLERANCING PER
   DIMENSIONING AND TOLERANCING PER
   ASME Y14.5 - 2009.
D) LOCATION OF THE PIN HOLE MAY VARY
   (LOWER LEFT CORNER, LOWER CENTER
   AND CENTER OF THE PACKAGE).
E) LANDPATTERN RECOMMENDATION PER IPC
   TO254P1524X482-3N
F) FILENAME: TO263A02REV7

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